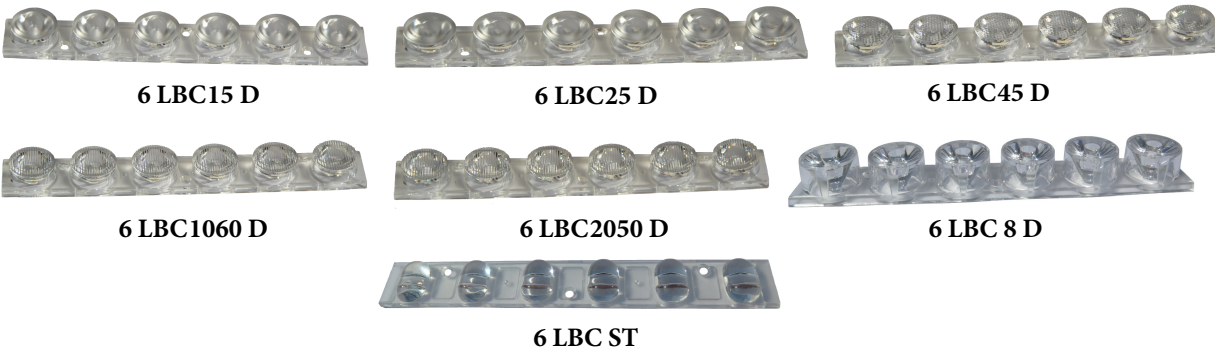


Size: 20 x 150 mm
 Thickness: 1,6 mm
 Weight: 11 g
 Electricity Line: Copper
 Thickness of copper: 35um
 Thickness of the dielectric: 70um
 Thickness of the aluminum-base: 1.5mm

Lenses for PCB 724-155:



The result of the test:

Item	Test item	Technology request	Unit	Test result	
1	Peel Strength	A	≥1.8	N/mm	2.0
	After thermal stress (260°C)	≥1.8	N/mm	1.8	
2	Blister test After Thermal stress (288°C , 2min)	288°C, 2 min No delaminating	/	Ok	
3	Thermal resistance	≤2.0	°C/W	1.0	
4	Thermal-Conductive Factor		W/m-k	1.0	
5	Flammability(A)	FV-O	/	FV-O	
6	Surface Resistivity	A	≥ 1×10 ⁵	MΩ	5×10 ⁷
	Constant humidity treatment (90%,35°C,96h)	≥ 1×10 ⁵	MΩ	2×10 ⁶	
7	Volume Resistivity	A	≥ 1×10 ⁶	MΩ·m	4×10 ⁸
	Constant humidity treatment (90%,35°C,96h)	≥ 1×10 ⁶	MΩ·m	5×10 ⁷	
8	Dielectric Breakdown(DC)	≥ 28.5	KV/MM	31	
9	Dielectric constant(1MHz) (40°C, 93%, 96h)	≤4.4	/	4.2	
10	Dielectric dissipation factor (1MHz) (40°C , 93% , 96h)	≤0.03	/	0.02	